

## Quad Array for ESD Protection

This quad monolithic silicon voltage suppressor is designed for applications requiring transient overvoltage protection capability. It is intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment, and other applications. Its quad junction common anode design protects four separate lines using only one package. These devices are ideal for situations where board space is at a premium.

### Specification Features

- SC88A Package Allows Four Separate Unidirectional Configurations
- Low Leakage < 1  $\mu$ A @ 3 Volt
- Breakdown Voltage: 6.1 Volt – 7.2 Volt @ 1 mA
- Low Capacitance (90 pF typical)
- ESD Protection Meeting IEC1000–4–2

### Mechanical Characteristics

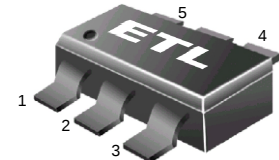
- Void Free, Transfer–Molded, Thermosetting Plastic Case
- Corrosion Resistant Finish, Easily Solderable
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications

[www.DataSheet4U.com](http://www.DataSheet4U.com)

### ORDERING INFORMATION

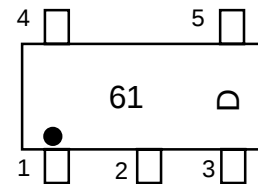
| Device    | Package | Shipping         |
|-----------|---------|------------------|
| MSQA6V1W5 | SC–88A  | 3000/Tape & Reel |

### MSQA6V1W5

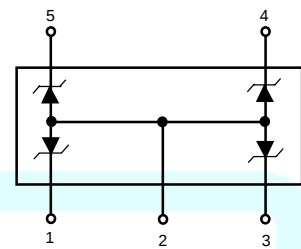


SOT–353/SC–88A  
CASE 419A

### MARKING DIAGRAM



61 = Device Marking  
D = One Digit Date Code



## MSQA6V1W5

### MAXIMUM RATINGS (T<sub>A</sub> = 25°C unless otherwise noted)

| Characteristic                                                             | Symbol                             | Value       | Unit  |
|----------------------------------------------------------------------------|------------------------------------|-------------|-------|
| Peak Power Dissipation @ 20 $\mu$ s @ T <sub>A</sub> $\leq$ 25°C (Note 1.) | P <sub>pk</sub>                    | 150         | Watts |
| Steady State Power – 1 Diode (Note 2.)                                     | P <sub>D</sub>                     | 385         | mW    |
| Thermal Resistance Junction to Ambient                                     | R <sub><math>\theta</math>JA</sub> | 325         | °C/W  |
| Above 25°C, Derate                                                         |                                    | 3.1         | mW/°C |
| Maximum Junction Temperature                                               | T <sub>JMax</sub>                  | 150         | °C    |
| Operating Junction and Storage Temperature Range                           | T <sub>J</sub> , T <sub>stg</sub>  | -55 to +150 | °C    |
| ESD Discharge                                                              |                                    |             |       |
| MIL STD 883C – Method 3015–6                                               | V <sub>PP</sub>                    | 16          | kV    |
| IEC1000–4–2, Air Discharge                                                 |                                    | 16          |       |
| IEC1000–4–2, Contact Discharge                                             |                                    | 9           |       |
| Lead Solder Temperature (10 seconds duration)                              | T <sub>L</sub>                     | 260         | °C    |

### ELECTRICAL CHARACTERISTICS

|           | Breakdown Voltage<br>V <sub>BR</sub> @ 1 mA (Volts) |     |     | Leakage Current<br>I <sub>RM</sub> @ V <sub>RM</sub> = 3 V | Capacitance<br>@ 0 V Bias | Max<br>V <sub>F</sub> @ I <sub>F</sub> = 200 mA |
|-----------|-----------------------------------------------------|-----|-----|------------------------------------------------------------|---------------------------|-------------------------------------------------|
| Device    | Min                                                 | Nom | Max | ( $\mu$ A)                                                 | (pF)                      | (V)                                             |
| MSQA6V1W5 | 6.1                                                 | 6.6 | 7.2 | 1.0                                                        | 90                        | 1.25                                            |

1. Non-repetitive current per Figure 1. Derate per Figure 2.
2. Only 1 diode under power. For all 4 diodes under power, P<sub>D</sub> will be 25%. Mounted on FR-4 board with min pad.

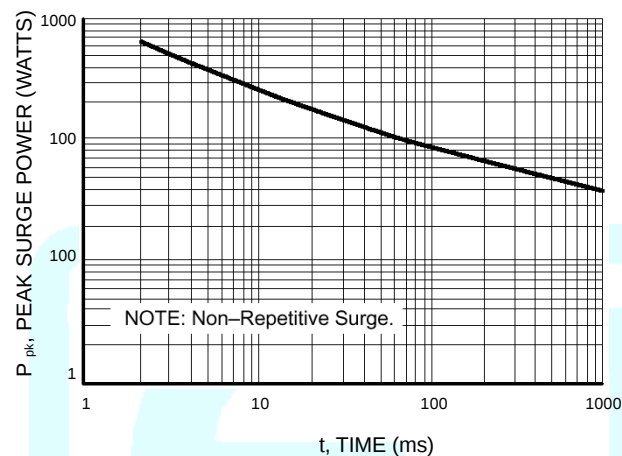


Figure 1. Pulse Width

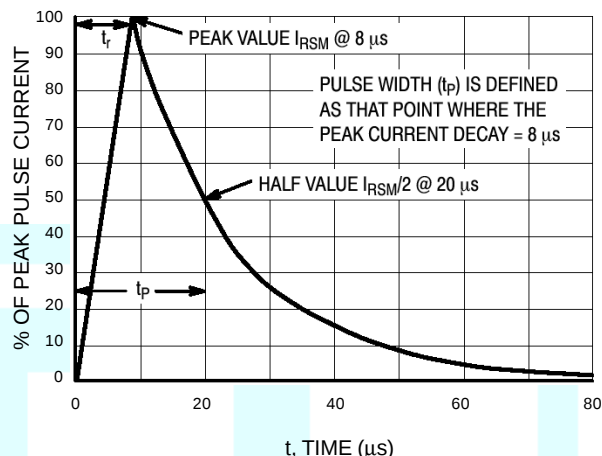


Figure 2. 8  $\times$  20  $\mu$ s Pulse Waveform

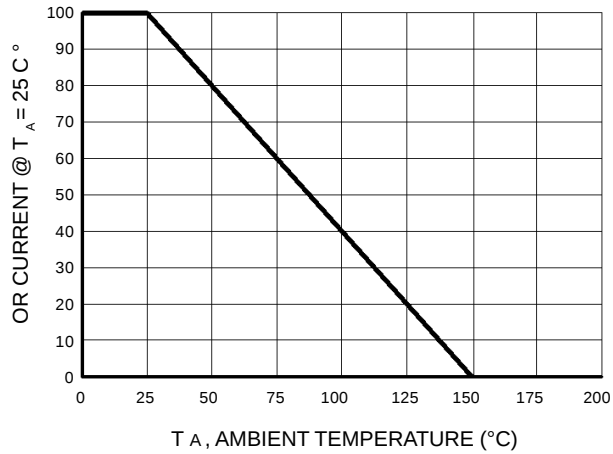


Figure 3. Pulse Derating Curve

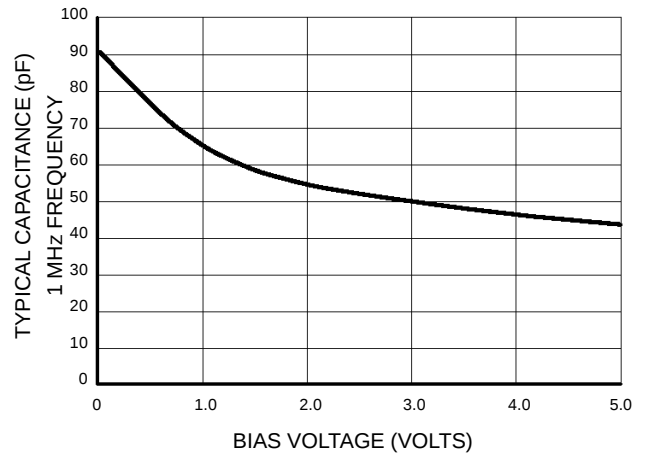


Figure 4. Capacitance

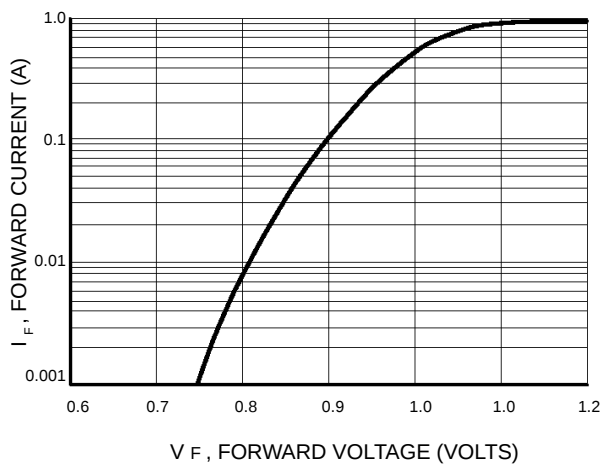


Figure 5. Forward Voltage

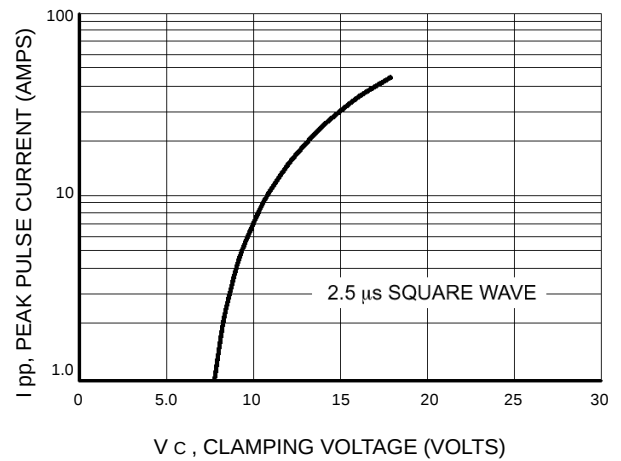


Figure 6. Clamping Voltage versus Peak Pulse Current (Reverse Direction)

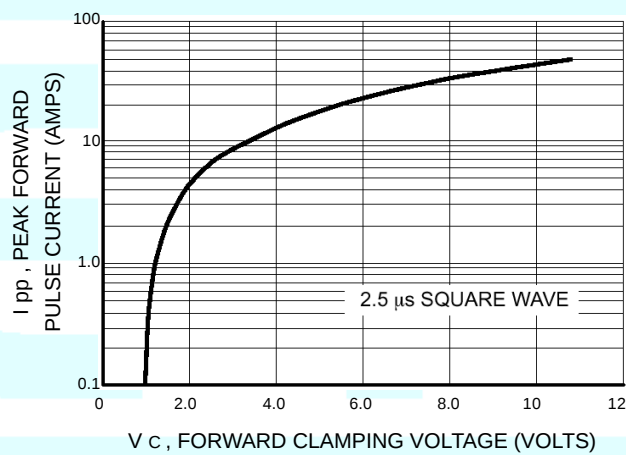


Figure 7. Clamping Voltage versus Peak Pulse Current (Forward Direction)